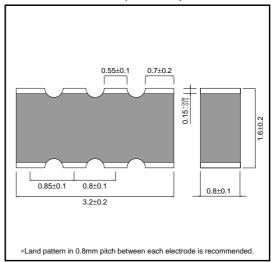
Multi-layer ceramic chip capacitor networks

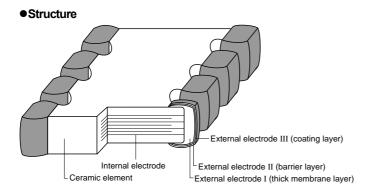
MNA14 (1608 (0603) × 4 size, chip capacitor networks)

Features

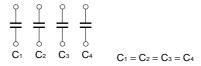
- 1) Area ratio is approximately 55% smaller than that of the MCH18, enabling high density mounting.
- 2) Mounting costs are reduced.
- Use of convex electrodes prevents solder bridging during mounting, and makes it easy to perform a visual inspection of the mounted piece. Also facilitates automatic inspection.
- 4) Barrier layer and end terminations to improve solderability.
- 5) Each element is independent to ensure a wide range of circuit applications.
- 6) Can be packed on tape.

• External dimensions (Units : mm)



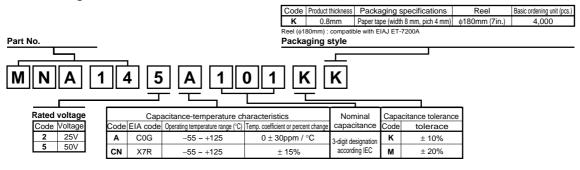


Equivalent circuits





Product designation



Capacitance range

Product name		MNA 14	
	Temperature characteristic	A (C0G)	CN (X7R)
Capacitance (pF)	Rated voltage	50V	25V
	Tolerance	K (± 10%)	M (± 20%)
10			
22			
47			
100			
220			
470			
1,000			
2,200			
4,700			
10,000			
22,000			
			XXXXXX

 $\begin{array}{c} & & \\ & & \\ \\ \mbox{Product thickness (mm)} & & 0.8 \pm 0.1 \end{array}$

*The design and specifications are subject to change without prior notice. Before ordering or using, please check the latest technical specification.

MNA14

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Characteristics

Class 1 (For thermal compensation)

Temperature characteristics		A (COG)	Test methods / conditions (based on JIS C 5102)	
Item				
Operating temperature		−55°C ~ +125°C		
Nominal capacitance (C) Dissipation factor (tanô)		Must be within the specified tolerance range. 100 / (400 + 20C)% or less: Less than 30 pF 0.1% or less : 30 pF or larger	Based on paragraph 7.8 and paragraph 9, Measured at room temperature and standard humidity Measurement frequency : 1 ± 0.1 MHz Measurement voltage : 1 ± 0.1 Vrms.	
Insulation resistance (IR)		10,000M\Omega or 500MΩ:µF, whichever is smaller	Based on paragraph 7.6. Measurement is made after rated voltage is applied for $60 \pm 5s$.	
Withstanding voltage		The insulation must not be damaged.	Based on paragraph 7.1. Apply 300% of the rated voltage for 1 to 5s then measure.	
Temperature characteristics		Within 0 \pm 30ppm / $^{\circ}\text{C}$	The temperature coefficients in table 12, paragraph 7.12 are calculated at 20°C and high temperature.	
Terminal adherence		No detachment or signs of detachment.	Based on paragraph 8.11.2. Apply 5N for 10 ± 1s in the direction indicated by the arrow. Pressure (5N Capacitor	
	Appearance	There must be no mechanical damage.	Chip is mounted to a board in the manner	
Resistance to vibration	Rate of capacitance change	Must be within initial tolerance.	shown on the right, subjected to vibration (type A in paragraph 8.2), and	
to vibration	Dissipation factor (tanδ)	Must satisfy initial specified value.	(type A in paragraph 8.2), and measured 24 ± 2 hours later. Board	
Solderability		At least 3/4 of the surface of the two terminals must be covered with new solder.	Based on paragraph 8.13, Soldering temperature $: 235 \pm 5^{\circ}$ C Soldering time $: 2 \pm 0.5s$	
	Appearance	There must be no mechanical damage.		
	Rate of capacitance change	$\pm2.5\%$ or ±0.25 pF, whichever is larger	1	
Resistance	Dissipation factor (tan b)	Must satisfy initial specified value.	Based on paragraph 8.14. Soldering temperature : $260 \pm 5^{\circ}$ C	
to soldering heat	Insulation resistance	10,000M Ω or 500M Ω μ F, whichever is smaller	Soldering time $:5 \pm 0.5s$ Preheating $:150 \pm 10^{\circ}C$ for 1 to 2 min.	
	Withstanding voltage	The insulation must not be damaged.		
	Appearance	There must be no mechanical damage.		
Terreture	Rate of capacitance change	\pm 2.5% or \pm 0.25 pF, whichever is larger	Based on paragraph 9.3, Number of cycles : 5	
Temperature cycling	Dissipation factor (Tanδ)	Must satisfy initial specified value.		
	Insulation resistance	10,000MΩ or 500MΩ· μ F, whichever is smaller	Capacitance measured after 24 ± 2 hrs.	
Humidity load - test	Appearance	There must be no mechanical damage.	Based on paragraph 9.9, Test temperature : $40 \pm 2^{\circ}$ C Relative humidity : 90% to 95% Applied voltage : rated voltage Test time : 500 to 524 hrs. Capacitance measured after 24 ± 2 hrs.	
	Rate of capacitance change	± 7.5% or ± 0.75 pF, whichever is larger		
	Dissipation factor (tanδ)	0.5% or less		
	Insulation resistance	500MΩ or 25MΩ·μF, whichever is smaller		
	Appearance	There must be no mechanical damage.	Based on paragraph 9.10, Test temperature : Max. operating temp.	
High-	Rate of capacitance change	\pm 3.0% or \pm 0.3 pF, whichever is larger		
temperature load test	Dissipation factor (tanδ)	0.3% or less	Applied voltage : rated voltage × 200% Test time : 1,000 to 1,048 hrs.	
	Insulation resistance	10,000MΩ or 50MΩ·μF, whichever is smaller	Capacitance measured after 24 ± 2 hrs.	

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MNA14

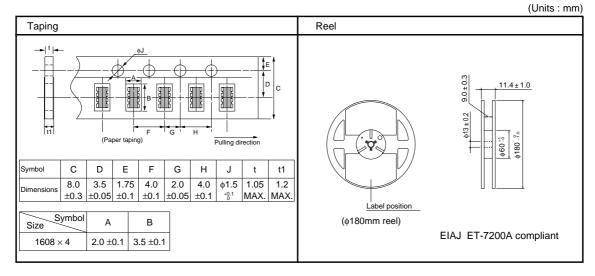
Class 2	(Hiah	dielectric	constant)
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Temperature characteristics		CN (X7R)	Test methods/conditions	
Item			(based on JIS C 5102)	
Operating temperature		−55°C ~ +125°C		
Nominal capacitance (C)		Must be within the specified tolerance range.	Based on paragraph 7.8 Measured at room temperature and standard humic Measurement frequency: 1 ± 0.1 kHz Measurement voltage $: 0.1 \pm 0.2$ Vrms.	
Dissipation factor (tan δ)		2.5% or less (when rated voltage is 16V : 3.5% or less)		
Insulation resistance (IR)		10,000M\Omega or 500MΩ $\mu\text{F},$ whichever is smaller	Based on paragraph 7.6 Measurement is made after rated voltage is applied for $60 \pm 5s$.	
Withstanding voltage		The insulation must not be damaged.	Based on paragraph 7.1 Apply 250% of the rated voltage for 1 to 5s then measure.	
Temperature characteristics		Within ± 15%	The temperature coefficients in paragraph 7.12, table 8, condition B, are based on measurements carried out at 20°C, with no voltage applied.	
Terminal adherence		No peeling or sign of peeling on terminal.	Based on paragraph 8.11.2. Apply 5N for 10 ± 1s in the direction indicated by the arrow.	
	Appearance	There must be no mechanical damage.	Chip is mounted to a board in the	
Resistance to vibration	Rate of capacitance change	Must be within initial tolerance.	manner shown on the right, subjected to vibration (type A in paragraph 8.2),	
	Dissipation factor (tanδ)	Must satisfy initial specified value.	and measured 48 \pm 4 hrs. later. Board	
Solderability		At least 3/4 of the surface of the two terminals must be covered with new solder.	Based on paragraph 8.13 Soldering temperature: 235 ± 5°C Soldering time : 2 ± 0.5s	
	Appearance	There must be no mechanical damage.	Based on paragraph 8.14. Soldering temperature: 260 ± 5°C Soldering time : 5 ± 0.5s	
	Rate of capacitance change	Within ± 5.0%		
Resistance to soldering	Dissipation factor (tanδ)	Must satisfy initial specified value.		
heat	Insulation resistance	10,000M\Omega or 500M Ω · μ F, whichever is smaller	Preheating : 150 ± 10°C fo 1 to 2 min.	
	Withstanding voltage	The insulation must not be damaged.		
	Appearance	There must be no mechanical damage.	Based on paragraph 9.3	
Temperature	Rate of capacitance change	Within ± 7.5%		
cycling	Dissipation factor (tanδ)	Must satisfy initial specified value.	Number of cycles : 5 Capacitance measured after 48 ± 4 h	
	Insulation resistance	10,000M\Omega or 500M Ω · μ F, whichever is smaller	1	
	Appearance	There must be no mechanical damage.	Based on paragraph 9.9 Test temperature : 40 ±2°C Relative humidity : 90% to 95% Applied voltage : rated voltage Test time : 500 to 524 hrs. Capacitance measured after 48 ± 4 hr	
Humidity load test	Rate of capacitance change	Within ± 12.5%		
	Dissipation factor ($tan\delta$)	5.0% or less		
	Insulation resistance	500M Ω or 25M Ω ·µF, whichever is smaller		
High- temperature load test	Appearance	There must be no mechanical damage.		
	Rate of capacitance change	Within ± 10.0%	Based on paragraph 9.10 Test temperature : Max. operating ter	
	Dissipation factor $(tan\delta)$	5.0% or less	Applied voltage : rated voltage × 200 Test time : 1,000 to 1,048 hrs. Capacitance measured after 48 ± 4 hr	
	Insulation resistance	1,000MΩ or 50MΩ· μ F, whichever is smaller		



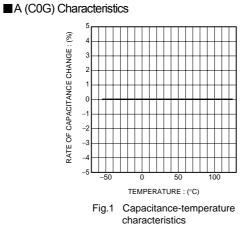
MNA14

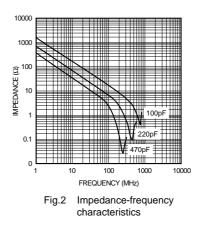
Packaging specifications



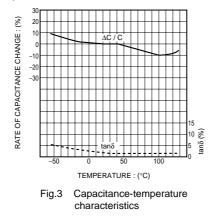


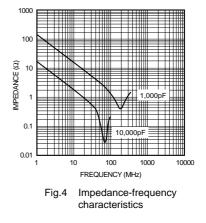
Electrical characteristics





CN (X7R) Characteristics





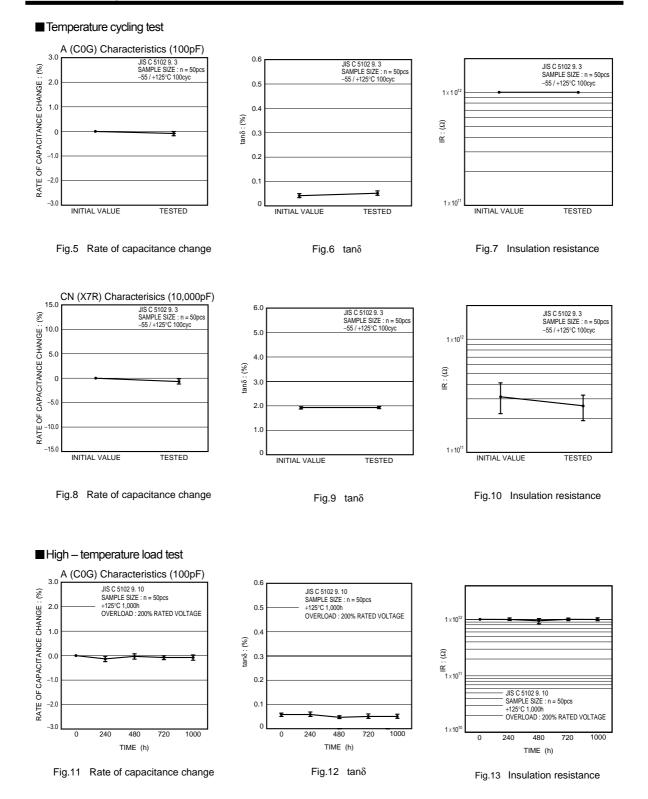
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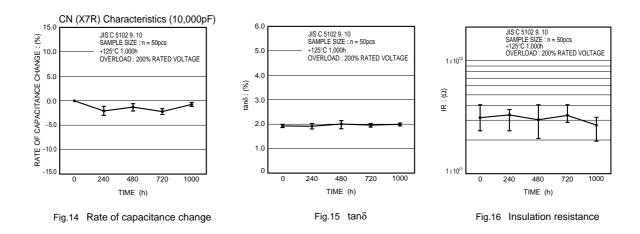
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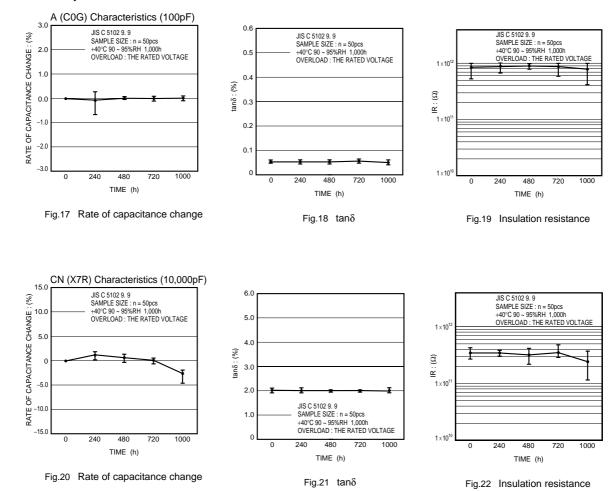
Ceramic capacitors







Humidity load test





Appendix

Notes

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